

## Supporting Information

### Integration of Material Sintering and p-n Connection for High-Performance PbTe Thermoelectric Modules

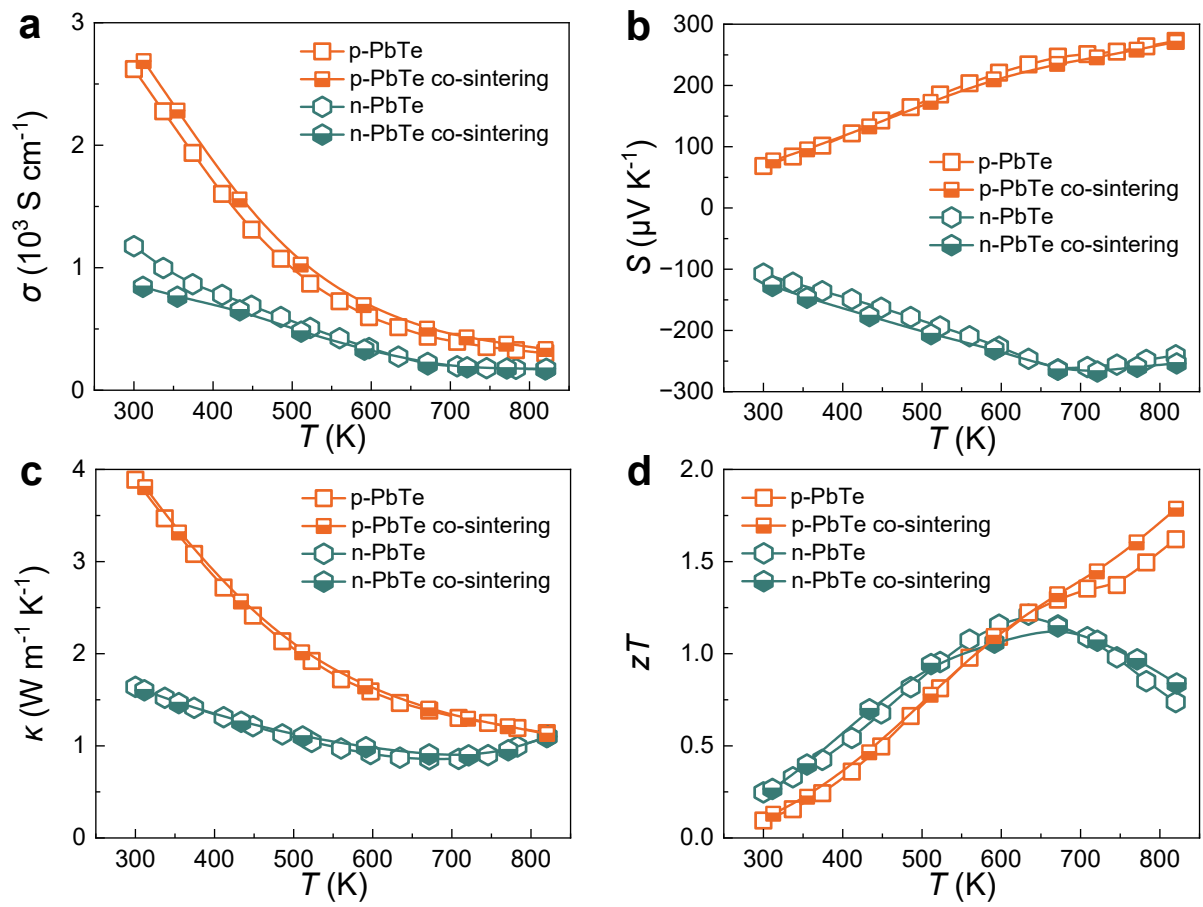
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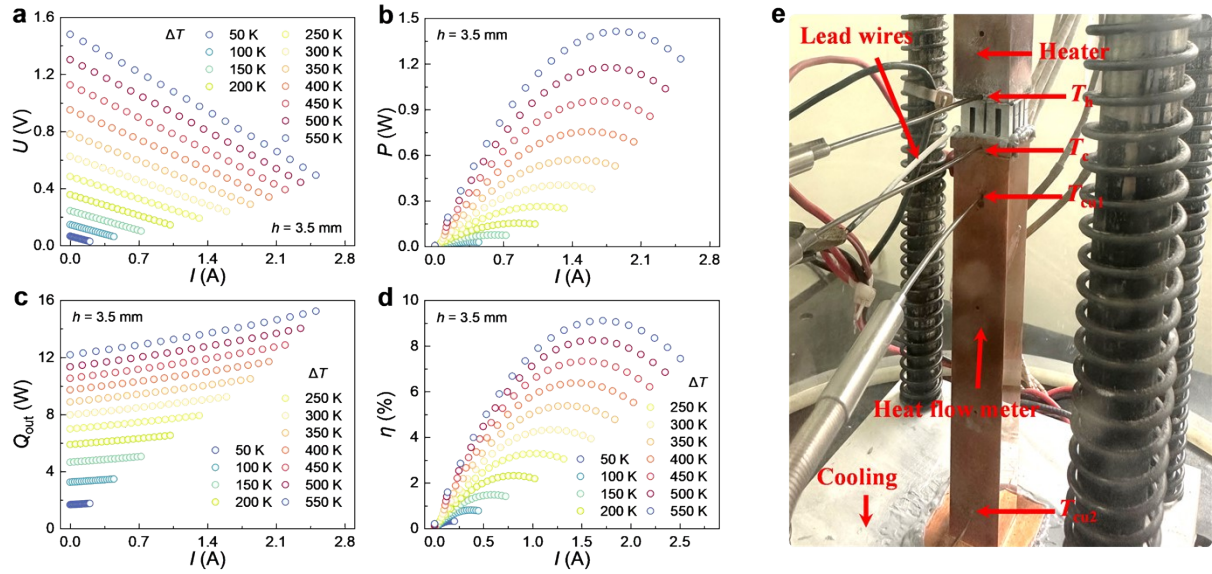
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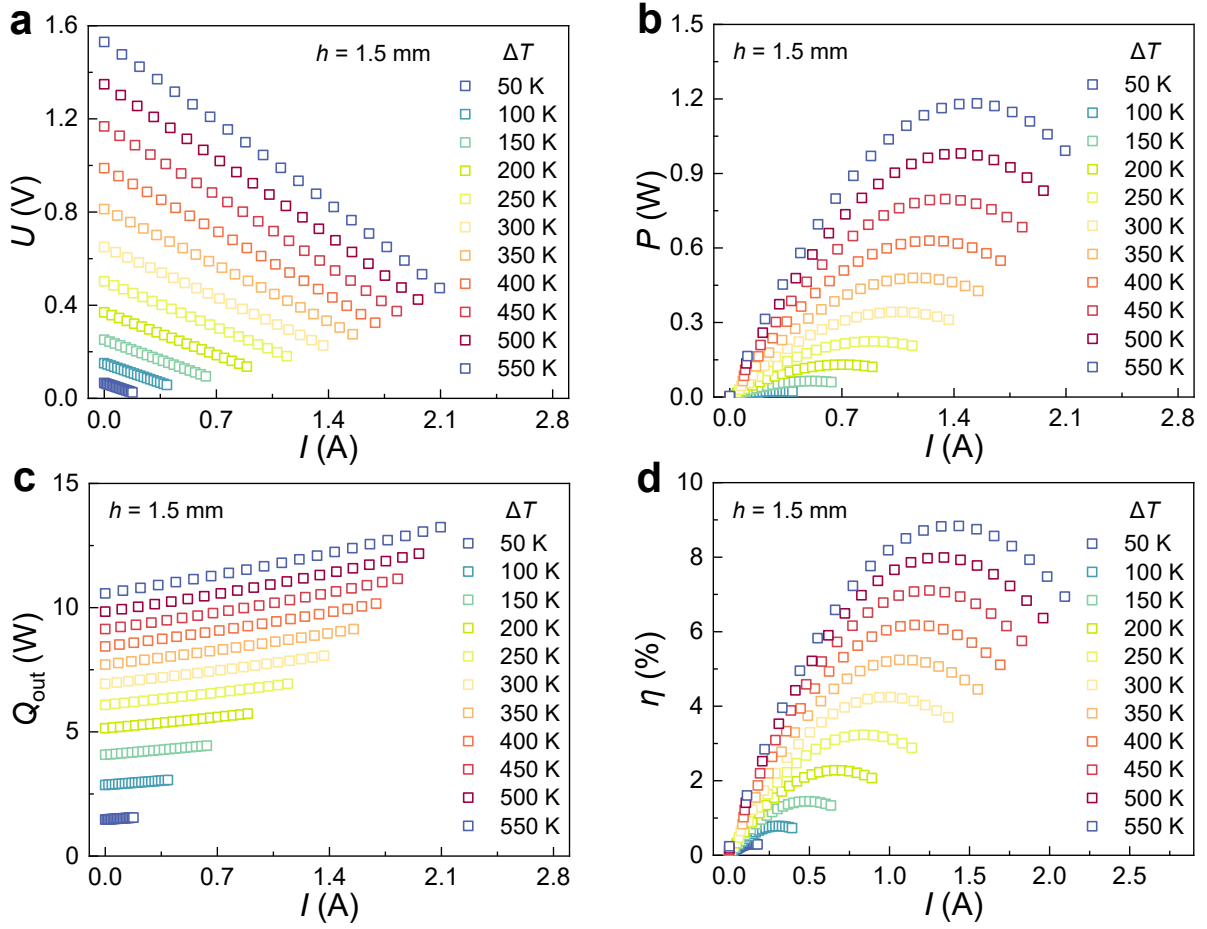
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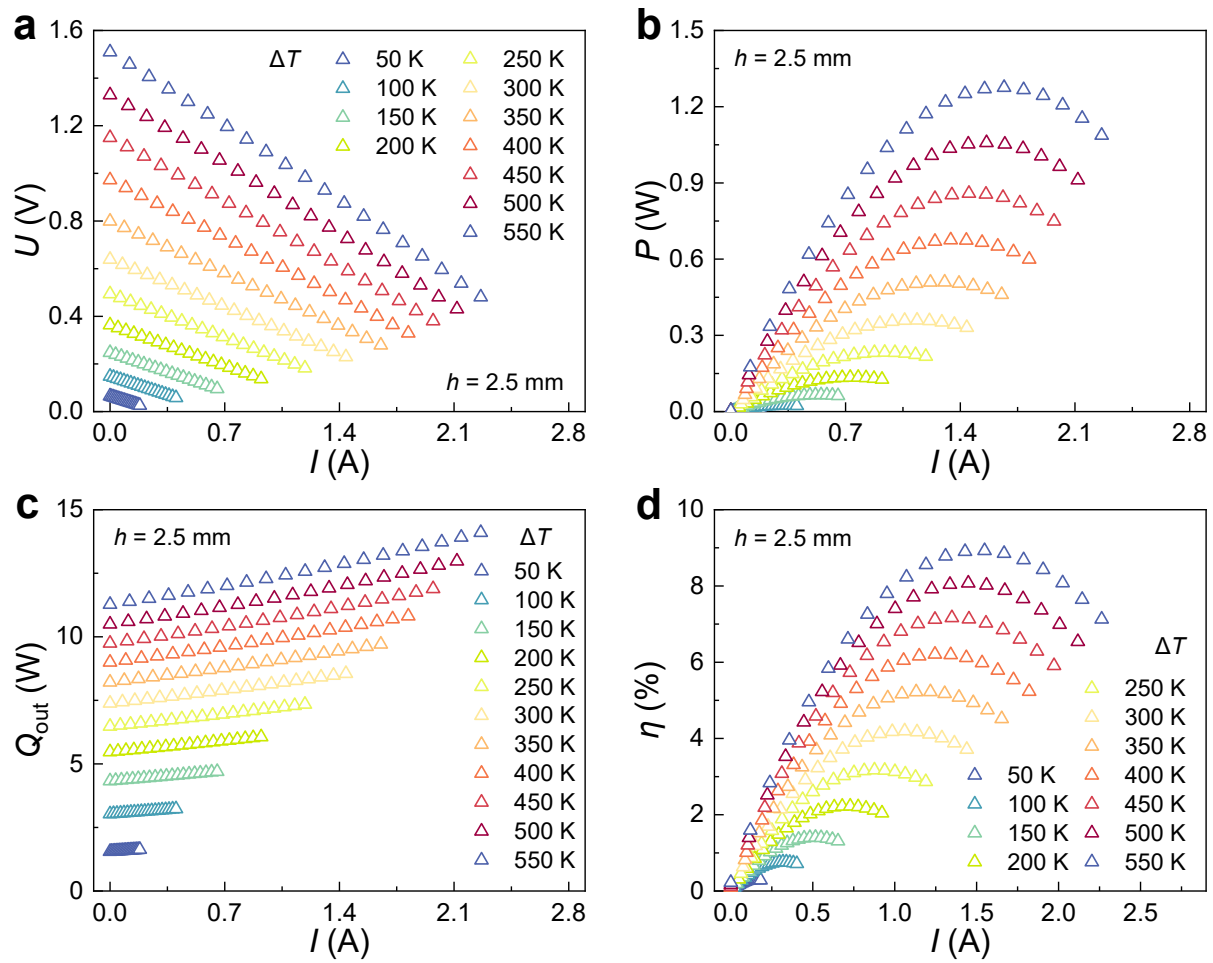
**Fig. S1.** Temperature-dependent (a) conductivity, (b) Seebeck coefficient, (c) thermal conductivity, and (d)  $zT$  of PbTe prepared by conventional sintering and PbTe prepared by co-sintering.



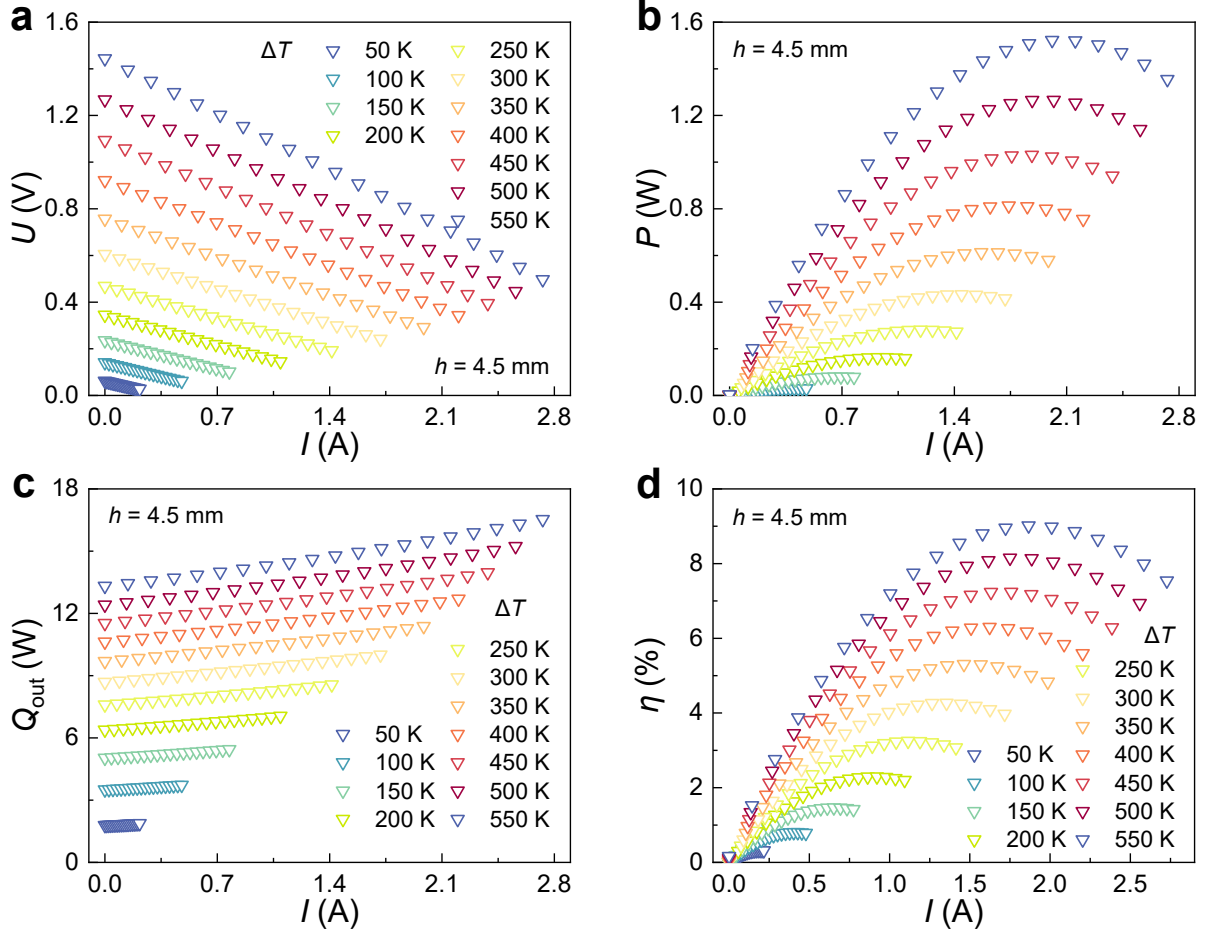
**Fig. S2.** Characterization of the U-shaped module. Current-dependent (a) output voltage, (b) output power, (c) heat flow out, and (d) efficiency for the module with  $h = 3.5$  mm under several temperature differences. (e) The experimental setup for module efficiency measurement.



**Fig. S3.** Characterization of the U-shaped module. Current-dependent (a) output voltage, (b) output power, (c) heat flow out, and (d) efficiency for the module with  $h = 1.5$  mm under several temperature differences.



**Fig. S4.** Characterization of the U-shaped module. Current-dependent (a) output voltage, (b) output power, (c) heat flow out, and (d) efficiency for the module with  $h = 2.5$  mm under several temperature differences.



**Fig. S5.** Characterization of the U-shaped module. Current-dependent (a) output voltage, (b) output power, (c) heat flow out, and (d) efficiency for the module with  $h = 4.5$  mm under several temperature differences.

**Table S1. Calculation of electronic transport properties**

Material properties	Ceramic plate ( $\text{Al}_2\text{O}_3$ )	Electrode (Cu)	p-leg ( $\text{Pb}_{0.98}\text{Na}_{0.02}\text{Te}$ )	n-leg ( $\text{Pb}_{0.9}\text{Ge}_{0.1}\text{Te}_{0.996}\text{I}_{0.004}$ )	SnTe	FeSb
Density ( $\text{kg m}^{-3}$ )	3940	8940	8090	7870	7300	8100
Thermal expansion coefficient ( $10^{-6} \text{ K}^{-1}$ )	7	16~18 (300 K~850 K)	20~21 (300 K~850 K)	18~21 (300 K~850 K)	18~20 (300 K~850 K)	15~20 (300 K~850 K)
Yang 's modulus	380	120	25	35	60	80

(GPa)						
Poisson ratio	0.25	0.33	0.25	0.25	0.30	0.30
Thermal conductivity ( $\text{W m}^{-1} \text{K}^{-1}$ )	30	400~230 (300 K~850 K)	3.9~1.1 (300 K~850 K)	1.3~0.9 (300 K~850 K)	15~2 (300 K~850 K)	20~3 (300 K~850 K)
Specific heat ( $\text{J kg}^{-1} \text{K}^{-1}$ )	780	382~431 (300 K~850 K)	150~170 (300 K~850 K)	150~170 (300 K~850 K)	190~300	180~300

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